



# Brands

## Background

Together with our customers, our Adhesive Technologies business has grown strongly in the past decades, both organically and through acquisitions. With this strategy, Henkel has become the global market leader in industrial adhesive and surface treatment technologies. However, we have also retained a large portfolio of product names and brands, which has become quite diverse and complex to navigate.

Therefore, we have regrouped our product offering and introduced a simplified branding approach. This means, we are using the Henkel brand more consistently and cluster our portfolio under clear Technology Cluster Brands, each of them representing a group of specific Henkel technologies. This approach ensures consistent worldwide naming of all of our products.



## Adhesive Electronics Technology Cluster Brands

- Simplification of the brand portfolio
- Two Adhesive Electronics Technology Cluster Brands, each of them representing a defined group of technologies
- Unified look and feel



Henkel's LOCTITE is the trusted choice for engineered high-performance adhesive, sealant and coating solutions.



Henkel's TECHNOMELT is the leading choice for hot melt adhesives designed for best results in your application and production process.



Excellence is our Passion

### Implementation of the new branding approach

The introduction of the new brand architecture will take place in phases from 2012 to 2015. We will keep you informed of all steps well in advance so that you can implement them in your systems and processes.

- TDSs will reflect the new product name.
- SDSs, shipping documents and invoices will reflect the legacy and new product name.

What will NOT change:

- **No change in chemical formulations. All products and technologies will stay the same.**
- Article Number (IDH Number) will not change.
- In most cases, there will be no changes in numeric codes.
- All certifications will remain valid.

### Adhesive Electronics Product Technologies

LOCTITE					
ABLESTIK	HYSOL	ECCOBOND	STYCAST	E&C*	
Die Attach	Mold Compounds	Underfills	PCB Protection	Inks and Coatings	Solder Materials
PCB Assembly Adhesives		Encapsulants			Thermal Management Materials
		Sealants			PCB Assembly Adhesives
		Semiconductor Assembly Adhesives			
		PCB Assembly Adhesives			
		Display Sealants			

\* E&C will replace the formerly known brand Acheson.

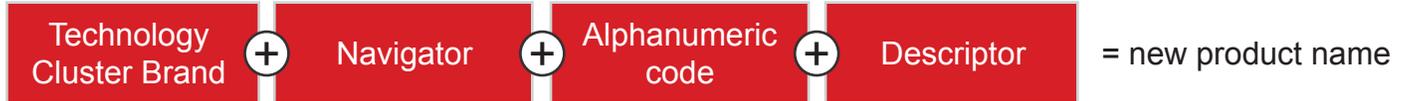
TECHNOMELT*
Low Pressure Molding

\* TECHNOMELT will replace the formerly known brand Macromelt.



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## Adhesive Electronics New Naming System



REBRANDED PRODUCT EXAMPLES				
New Product Name				Formerly Known As
Technology Cluster Brand	Navigator	Alphanumeric Code	Descriptor*	
LOCTITE	ABLESTIK	5025E-002		Ablefilm 5025E-002
LOCTITE	TCF	1000 AL		Thermstrate AL-S 2.44 x 2.36
LOCTITE	STYCAST	1090		Stycast 1090 2 KG

\*Additional product descriptor is not required for all products.

## The Bergquist Company

Henkel acquired The Bergquist Company, a privately-held leading supplier of thermal-management solutions for the electronics industry worldwide, in Sept. 2014. At this time, all Bergquist products will remain branded under the well-respected brands of Gap Pad®, Gap Filler, Thermal Clad®, Sil-Pad®, Liqui-Form® and Bond-Ply.